HSL-6002

Cup Cover Film Heat Seal

Application

HSL-6002 is professionally designed for the determination of heat sealability of various kinds cup cover films of yogurt cups, instant noodles, capsule coffee cups, jelly cups etc. Heat sealability of film depends on heat seal temperature, heat seal pressure and heat dwell time.

Features

1: Professional for cup cover film heat sealing test

2: Embedded system control, patent technology

3: Touch screen operation, easy to operate

4: TFT LCD display, UI flattening design

5: Flexible cup support frame, customized available

6: Micro-printer prints mini-report

7: Pressure easy to adjust, heat temperature and time touch screen input.

8: Emergency stop button, safety design to prevent burns

9: Over temperature protection, over pressure protection

10: Silence working without cooling fans

11: DB9 RS232 communication port.

12: DSM system is optional(Laboratory Management Information System), easy to manage and share test data.

Technical Indexes

Heat temperature: Room temperature+6 - 300℃

Accuracy: ±0.2 ℃

Dell time: 0.1- 999.9s

Pressure: 0.05 MPa-1.0MPa

Max cover film area: 265mm × 90 mm

Cup frame: 280mm × 145 mm × 105 mm (customized available)

Cup model: 66mm, 63mm, 58 mm (customized available)

Gas source pressure: 0.05MPa - 1.0MPa (self-provide)

Gas source interface: Φ6mm

Outer dimension: 570 mm (L)×500 mm (W)×470 mm (H)

Work noise: 0db

Power supply: AC 220V 50Hz

Net weight: 63kg

Standards

QB/T 2358(ZBY 28004), ASTM F2029, YBB 00122003

Configuration

Standard configuration: main unit, micro-printer, footswitch.

Optional: Customized cup frame, Film clip, Communication cable, DSM system

Note: Specifications are subject to change without prior notice.